

## **AMENDMENTS TO THE CLAIMS:**

Without prejudice, this listing of the claims replaces all prior versions and listings of the claims in the present application:

### **Listing of Claims:**

1. (Original) A microstructured component having a layered construction, comprising:
  - a carrier including at least one glass layer;
  - a component structure including a first silicon layer bonded to the glass layer; and
  - a cap arranged over the component structure and bonded to the glass layer.
2. (Canceled)
3. (Original) The microstructured component of claim 1, wherein the component structure includes a first silicon wafer and is bonded to the glass layer by anodic bonding.
4. (Original) The microstructured component of claim 3, wherein the first silicon wafer includes a (111)-silicon wafer.
5. (Original) The microstructured component of claim 1, wherein the cap includes a second silicon wafer and is bonded to the glass layer by anodic bonding.
6. (Original) The microstructured component of claim 1, further comprising conductor paths arranged to contact the component structure arranged between the glass layer and the component structure.
7. (Original) The microstructured component of claim 1, further comprising at least one electrically conductive shield arranged on the glass layer, at least part of the component structure electrically connected to the shield.
8. (Original) The microstructured component of claim 7, wherein the glass layer includes a structured metallization in which conductor paths and shields are arranged.
9. (Original) The microstructured component of claim 1, wherein the component structure is enclosed in a vacuum between the glass layer and the cap.

10.-21. (Canceled)